

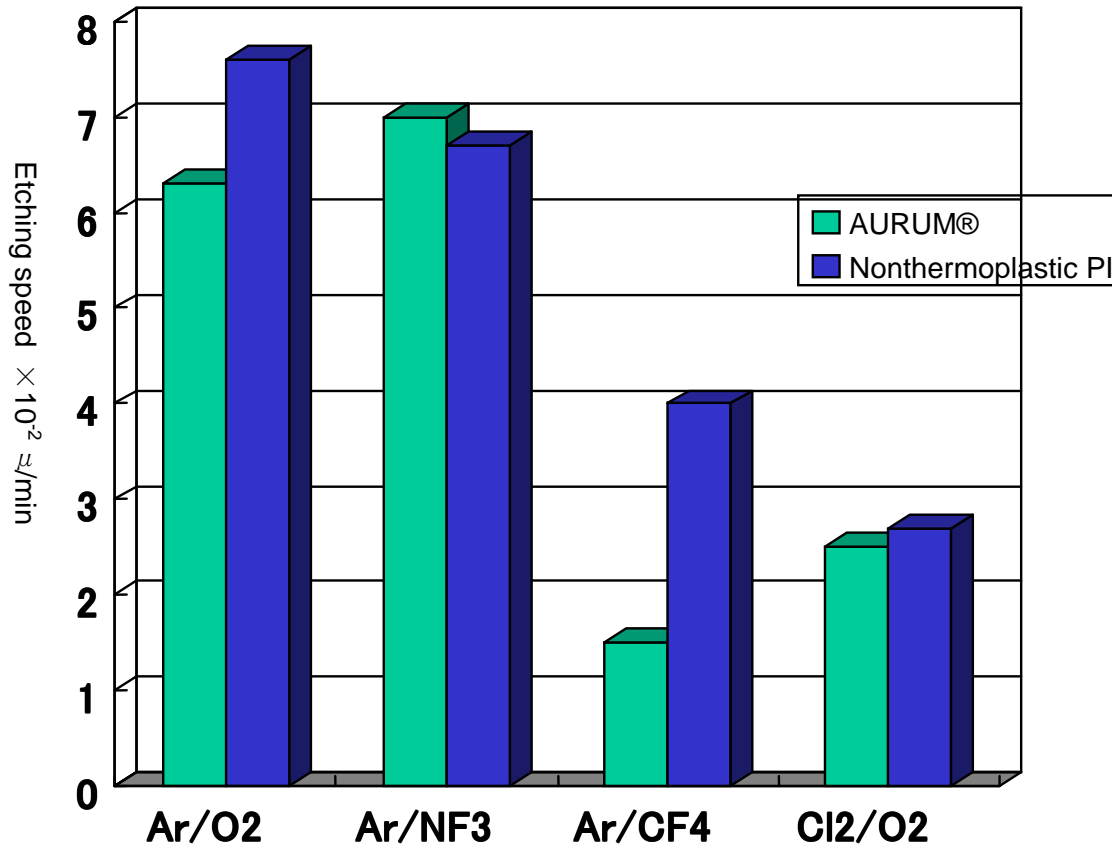
Technical Literature F-08

Plasma Resistance of AURUM[®]

AURUM[®] has plasma resistance equal to or higher than that of non-thermoplastic polyimide having a good track record in this property. Because of this, AURUM[®] can be used for the semiconductor applications such as plasma etching equipment.

Fig. 1 shows etching speed and plasma conditions.

Fig. 1 Etching Speed and Plasma Conditions



Plasma conditions:

Processing time: 60 min

Processing pressure: 1 ton

Electrode pressure: 100 ev

The information contained herein is based on the information and data available at this moment, but none of the data or evaluation results contained herein provide any warranty whatsoever.